

Day : Monday
Date: 4/12/2004

Time: 09:22:06

PALM INTRANET

Inventor Name Search Result

10/026,378

Your Search was:

Last Name = CHOU

First Name = JING-PEI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 3
10124575 2020167888	Not Issued	041 mine	04/16/2002	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS	CHOU, JING-PEI IFW
10026378 This case	Not Issued	071	12/21/2001	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS	CHOU, JING-PEI
09632486	6509274	150	08/04/2000	METHOD FOR FORMING ALUMINUM LINES OVER ALUMINUM-FILLED VIAS IN A SEMICONDUCTOR SUBSTRATE	CHOU, JING-PEI

Inventor Search Completed: No Records to Display.

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Day : Monday
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PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = KAO

First Name = CHIEN-TEH

Application#	Patent#	Status	Date Filed	Title	Inventor Name 15
<u>60447372</u>	Not Issued	020	02/14/2003	SUBSTRATE CLEANING WITH HYDROGEN PLASMA	KAO, CHIEN-TEH
<u>60305307</u>	Not Issued	159	07/13/2001	PULSE NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS	KAO, CHIEN-TEH
<u>10194442</u>	Not Issued	160 <i>abd</i>	07/12/2002	PULSED NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS	KAO, CHIEN-TEH
<u>10124575</u>	Not Issued	041	04/16/2002	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS	KAO, CHIEN-TEH
<u>10026378</u>	Not Issued	071	12/21/2001	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS	KAO, CHIEN-TEH
<u>10023125</u>	Not Issued	019	12/17/2001	PULSE NUCLEATION ENHANCED NUCLEATION TECHNIQUE FOR IMPROVED STEP COVERAGE AND BETTER GAP FILL FOR WCVD PROCESS	KAO, CHIEN-TEH <i>not IFW no pre-pub</i>
<u>09973403</u>	Not Issued	161 <i>abd</i>	10/08/2001	METHOD OF FORMING A SILICON NITRIDE LAYER ON A SEMICONDUCTOR WAFER	KAO, CHIEN-TEH
<u>09916967</u>	Not Issued	161 <i>abd</i>	07/27/2001	APPARATUS FOR IMPROVED REMOTE MICROWAVE PLASMA SOURCE FOR USE	KAO, CHIEN-TEH

				WITH SUBSTRATE PROCESSING SYSTEMS	
<u>09603117</u>	<u>6461435</u>	150	06/22/2000 X	SHOWERHEAD WITH REDUCED CONTACT AREA	KAO, CHIEN-TEH
<u>09602657</u>	Not Issued	161 dd	01/01/0001	LID ASSEMBLY FOR A SEMICONDUCTOR PROCESSING CHAMBER	KAO, CHIEN-TEH
<u>09593586</u>	<u>6603269</u>	150	06/13/2000 X	RESONANT CHAMBER APPLICATOR FOR REMOTE PLASMA SOURCE	KAO, CHIEN-TEH
<u>09416861</u>	<u>6271148</u>	150	10/13/1999 X	METHOD FOR IMPROVED REMOTE MICROWAVE PLASMA SOURCE FOR USE WITH SUBSTRATE PROCESSING SYSTEMS	KAO, CHIEN-TEH
<u>09350810</u>	<u>6645884</u>	150	07/09/1999 X	METHOD OF FORMING A SILICON NITRIDE LAYER ON A SUBSTRATE	KAO, CHIEN-TEH
<u>08893922</u>	<u>6125859</u>	150	07/11/1997 ✓	METHOD FOR IMPROVED CLEANING OF SUBSTRATE PROCESSING SYSTEMS	KAO, CHIEN-TEH
<u>08839111</u>	<u>6026762</u>	150	04/23/1997 ✓	APPARATUS FOR IMPROVED REMOTE MICROWAVE PLASMA SOURCE FOR USE WITH SUBSTRATE PROCESSING SYSTEMS	KAO, CHIEN-TEH

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name	
<input type="text" value="kao"/>	<input type="text" value="chien-teh"/>	<input type="button" value="Search"/>

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Day : Monday
Date: 4/12/2004

Time: 09:43:27



PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = LAI

First Name = CHIUKIN

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w/ore
chiuse

Application#	Patent#	Status	Date Filed	Title	Inventor Name 3
<u>60447372</u>	Not Issued	020	02/14/2003	SUBSTRATE CLEANING WITH HYDROGEN PLASMA	LAI, CHIUKIN STEVEN
<u>10124575</u>	Not Issued	041	04/16/2002	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS	LAI, CHIUKIN
<u>10026378</u>	Not Issued	071	12/21/2001	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS	LAI, CHIUKIN STEVEN

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name

First Name

lai

chiukin

Search

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Day : Monday
Date: 4/12/2004

Time: 09:44:18

PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = LAI

First Name = STEVEN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 6
<u>09559020</u>	<u>6323705</u>	150	04/25/2000	DOUBLE CYCLE LOCK APPROACH IN DELAY LOCK LOOP CIRCUIT	LAI, STEVEN
<u>09557521</u>	<u>6333959</u>	150	04/25/2000	CROSS FEEDBACK LATCH- TYPE BI-DIRECTIONAL SHIFT REGISTER IN A DELAY LOCK LOOP CIRCUIT	LAI, STEVEN
<u>09453558</u>	<u>6281428</u>	150	12/03/1999	PHOTOVOLTAIC GENERATOR	LAI , STEVEN
<u>08848765</u>	Not Issued	161	05/01/1997	TELESCOPING PORTABLE BACK SCRATCHER	LAINER , STEVEN D.
<u>08638425</u>	Not Issued	161	04/26/1996	BUSINESS BIBS	LAINER , STEVEN D
<u>08546444</u>	Not Issued	166	10/23/1995	TELESCOPING PORTABLE BACK SCRATCHER	LAINER , STEVEN D.

Inventor Search Completed: No Records to Display.

Search Another: Inventor Last Name First Name

<input type="text" value="lai"/>	<input type="text" value="steven"/>	<input type="button" value="Search"/>
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Day : Monday
Date: 4/12/2004

PALM INTRANET

Time: 09:56:23

Inventor Name Search Result

Your Search was:

Last Name = CHEN

First Name = FUFA

Application#	Patent#	Status	Date Filed	Title	Inventor Name 10
10038199	6660135	150	12/21/2001	STAGED ALUMINUM DEPOSITION PROCESS FOR FILLING VIAS	CHEN, FUFA
10026378	Not Issued	071	12/21/2001	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS	CHEN, FUFA
09721337	6332601	150	11/22/2000	LIQUID VAPORIZERS FOR SEMICONDUCTOR PROCESSING SYSTEMS	CHEN, FUFA
09497787	6436820	150	02/03/2000	METHOD FOR THE CVD DEPOSITION OF A LOW RESIDUAL HALOGEN CONTENT MULTI-LAYERED TITANIUM NITRIDE FILM HAVING A COMBINED THICKNESS GREATER THAN 1000 ANGSTROMS	CHEN, FUFA
09421779	6364949	150	10/19/1999	300MM CVD CHAMBER DESIGN FOR METAL-ORGANIC THIN FILM DEPOSITION	CHEN, FUFA
09340977	6352620	150	06/28/1999	STAGED ALUMINUM DEPOSITION PROCESS FOR FILLING VIAS	CHEN, FUFA
09248869	6221174	150	02/11/1999	METHOD OF PERFORMING TITANIUM/TITANIUM NITRIDE INTEGRATION	CHEN, FUFA
09064359	6179277	150	02/27/1998	LIQUID VAPORIZER SYSTEMS AND METHODS FOR THEIR USE	CHEN, FUFA
08976961	6220091	150	11/24/1997	LIQUID LEVEL PRESSURE SENSOR AND METHOD	CHEN, FUFA
08893811	6086676	150	07/11/1997	PROGRAMMABLE	CHEN, FUFA

				ELECTRICAL INTERLOCK SYSTEM FOR A VACUUM PROCESSING SYSTEM	
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Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name	Search
	<input type="text" value="chen"/>	<input type="text" value="fufa"/>	

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Day : Monday
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PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = CHANG

First Name = MEI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>60426134</u>	Not Issued	020	11/14/2002	APPARATUS AND METHOD FOR HYBRID CHEMICAL PROCESSING	CHANG, MEI
<u>60333200</u>	Not Issued	159	11/16/2001	ATOMIC LAYER DEPOSITION OF COPPER USING A REDUCING GAS AND NON-FLUORINATED COPPER PRECURSORS	CHANG, MEI
<u>60325712</u>	Not Issued	159	09/28/2001	METHOD AND APPARATUS FOR PLASMA CLEANING OF COPPER	CHANG, MEI
<u>60306027</u>	Not Issued	159	07/16/2001	ATOMIC LAYER DEPOSITION TiCl ₄ TIN AND 300MM ATOMIC LAYER DEPOSITION TUNGSTEN	CHANG, MEI
<u>29148843</u>	D458962	150	09/25/2001	TONER CARTRIDGE	CHANG, MEI HSIA
<u>29148842</u>	D473588	150	09/25/2001	TONER CARTRIDGE	CHANG, MEI HSIA
<u>29148841</u>	D458961	150	09/25/2001	TONER CARTRIDGE	CHANG, MEI HSIA
<u>29148840</u>	D458960	150	09/25/2001	TONER CARTRIDGE	CHANG, MEI HSIA
<u>29148839</u>	D458302	150	09/25/2001	TONER CARTRIDGE	CHANG, MEI HSIA
<u>10743876</u>	Not Issued	019	12/24/2003	ACTIVE MATRIX ORGANIC ELECTROLUMINESCENT PANEL	CHANG, MEI-YING
<u>10741824</u>	Not Issued	019	12/19/2003	ENHANCEMENT OF CU LINE RELIABILITY USING THIN ALD TAN FILM TO CAP THE CU LINE	CHANG, MEI
<u>10717013</u>	Not	030	11/19/2003	SUPPORT STAND ASSEMBLY	CHANG, MEI-LI

Pat.
Design
No
No
No

	Issued			FOR A COMPUTER DESK	
10716096	Not Issued	020	11/18/2003	CHAMBER FOR CONSTRUCTING A FILM ON A SEMICONDUCTOR WAFER	CHANG, MEI
10712690	Not Issued	019 1734	11/13/2003 11/8/—?	APPARATUS AND METHOD FOR HYBRID CHEMICAL ? PROCESSING	CHANG, MEI IFW
10634662	Not Issued	030	08/04/2003	RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION	CHANG, MEI
10299212	Not Issued	041	11/18/2002	FORMATION OF COMPOSITE TUNGSTEN FILMS	CHANG, MEI
10295770	Not Issued	061	11/15/2002	ATOMIC LAYER DEPOSITION OF COPPER USING A REDUCING GAS AND NON-FLUORINATED COPPER PRECURSORS	CHANG, MEI
10281079	Not Issued	041	10/25/2002	GAS DELIVERY APPARATUS FOR ATOMIC LAYER DEPOSITION	CHANG, MEI
10248113	6608333	150	12/19/2002	ORGANIC LIGHT EMITTING DIODE DEVICE	CHANG, MEI-YING
10124575	Not Issued	041	04/16/2002	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION (CVD) PROCESS	CHANG, MEI
10124309	Not Issued	071	04/16/2002	MULTI-STATION DEPOSITION APPARATUS AND METHOD	CHANG, MEI
10052681	Not Issued	094	01/17/2002	RELIABILITY BARRIER INTEGRATION FOR CU APPLICATION	CHANG, MEI
10050818	Not Issued	071	01/18/2002	METHOD OF A HIGH STABILITY SELECTABLE HYDROGENATE CATALYST PRODUCING AND USING FOR DMCHD MANUFACTURING	CHANG, MEI-YUAN
10047382	6705246	150	01/14/2002	RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG, MEI
10043544	6533894	150	01/10/2002	RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND	CHANG, MEI

				METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	
10026378	Not Issued	071	12/21/2001	METHOD OF TISIN DEPOSITION USING A CHEMICAL VAPOR DEPOSITION PROCESS	CHANG, MEI
10015433	Not Issued	121	12/12/2001	METHOD AND APPARATUS FOR CLEANING SUBSTRATES	CHANG, MEI
09965373 20030057027	Not Issued	071 2814	09/26/2001 458/1687	INTEGRATION OF BARRIER LAYER AND SEED LAYER	CHANG, MEI FFW
09965370 20030059539	Not Issued	041 1762	09/26/2001 427/248.1	INTEGRATION OF BARRIER LAYER AND SEED LAYER	CHANG, MEI IFW - Enc. Full
09965369 20030057526	Not Issued	120 2814	09/26/2001 257/642	INTEGRATION OF BARRIER LAYER AND SEED LAYER	CHANG, MEI NOT FFW
09964108	6607976	150	09/25/2001	COPPER INTERCONNECT BARRIER LAYER STRUCTURE AND FORMATION METHOD	CHANG, MEI
09960469 2003 0049991 20020197865	Not Issued	041 2818 458/1448	09/19/2001	FORMATION OF REFRACTORY METAL NITRIDES USING CHEMISORPTION TECHNIQUES	CHANG, MEI NOT FFW
09949228	6690904	150	09/07/2001	DEVELOPER CONTAINER	CHANG, MEI HSIA
09885609	Not Issued	092 2918 438/679	06/20/2001	SYSTEM AND METHOD TO FORM A COMPOSITE FILM STACK UTILIZING SEQUENTIAL DEPOSITION TECHNIQUES	CHANG, MEI FFW
09882696	Not Issued	161 ad	06/15/2001	INTEGRATED BARRIER LAYER STRUCTURE FOR COPPER CONTACT LEVEL METALLIZATION	CHANG, MEI
09882182	Not Issued	164 ad	06/18/2001	PACKAGING STRUCTURE OF A CHIP	CHANG, MEI-HUI
09880465	Not Issued	041	06/12/2001	LOW-RESISTIVITY TUNGSTEN FROM HIGH-PRESSURE CHEMICAL VAPOR DEPOSITION USING METAL-ORGANIC PRECURSOR	CHANG, MEI
09874882	6482746	150	06/05/2001	COMPUTER READABLE MEDIUM FOR CONTROLLONG A METHOD OF CLEANING A PROCESS CHAMBER	CHANG, MEI

09755009	Not Issued	161 <i>del</i>	01/05/2001	DEPOSITION OF TUNGSTEN NITRIDE BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG, MEI
09737154	6326690	150	12/14/2000	METHOD OF TITANIUM/TITANIUM NITRIDE INTEGRATION	CHANG, MEI
09706321	6355106	150	11/03/2000	DEPOSITION OF COPPER WITH INCREASED ADHESION	CHANG, MEI
09670982	6235646	150	09/26/2000 ?	RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA-ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG, MEI
09667315	Not Issued	161 <i>del</i>	09/22/2000	PROCESS FOR MANUFACTURING A SHOE SOLE	CHANG, MEI-YUN
09608659	6402806	150	06/30/2000	METHOD FOR UNREACTED PRECURSOR CONVERSION AND EFFLUENT REMOVAL	CHANG, MEI
09598839	Not Issued	030	06/21/2000	MULTIPLE FILE SEGMENT PLAYBACK FOR MPEG PRODUCT	CHANG, MEICHIH
09593018	6270621	150	06/13/2000	ETCH CHAMBER	CHANG, MEI
09569737	Not Issued	161 <i>del</i>	05/11/2000	METHOD OF TITANIUM/TITANIUM NITRIDE INTEGRATION	CHANG, MEI
09495555	6555183	150	02/01/2000	PLASMA TREATMENT OF A TITANIUM NITRIDE FILM FORMED BY CHEMICAL VAPOR DEPOSITION	CHANG, MEI
09491618	Not Issued	160 <i>del</i>	01/26/2000	INLET MANIFOLD AND METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG, MEI
09330696	6548402	150	06/11/1999	METHOD OF DEPOSITING A THICK TITANIUM NITRIDE FILM	CHANG, MEI
09162336	6193813	150	09/28/1998	UTILIZATION OF SIH4 SOAK AND PURGE IN DEPOSITION PROCESSES	CHANG, MEI

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PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = CHANG

First Name = MEI

Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>60478663</u>	Not Issued	020	06/13/2003	INTEGRATION OF ALD TANTALUM NITRIDE FOR COPPER METALLIZATION	CHANG, MEI
<u>60477478</u>	Not Issued	020	06/05/2003	APPARATUS FOR GENERATING A PRECURSOR FOR A SEMICONDUCTOR PROCESSING SYSTEM	CHANG, MEI
<u>60438479</u>	Not Issued	020	01/07/2003	ENHANCE OF CU LINE RELIABILITY USING THIN ALD TAN FILM TO CAP THE CU LINE	CHANG, MEI
<u>60397230</u>	Not Issued	159	07/19/2002	DEPOSITION APPARATUS	CHANG, MEI
<u>60385715</u>	Not Issued	159	06/04/2002	DEPOSITION OF COPPER FILMS	CHANG, MEI
<u>60385499</u>	Not Issued	159	06/04/2002	NOBLE METAL LAYER FORMATION FOR COPPER FILM DEPOSITION	CHANG, MEI
<u>10602836</u>	Not Issued	030	06/24/2003	MICRODERMABRASION CANISTER RACK SYSTEM	CHANG, MEI YIN
<u>10447255</u>	Not Issued	041	05/27/2003	METHOD AND APPARATUS OF GENERATING PDMAT PRECURSOR	CHANG, MEI
<u>10443648</u>	Not Issued	030	05/22/2003	NOBLE METAL LAYER FORMATION FOR COPPER FILM DEPOSITION	CHANG, MEI
<u>10441242</u>	Not Issued	030	05/19/2003	DEPOSITION OF COPPER FILMS	CHANG, MEI
<u>10427904</u>	Not Issued	030	05/02/2003	ORGANIC LIGHT-EMITTING DIODE DEVICE WITH A FUNCTION OF LATERAL LIGHT UTILIZATION, METHOD FOR UTILIZING THE SAME AND	CHANG, MEI-YING

				DEVICE WITH INFORMATION DISPLAY AND BACK-LIGHT EFFECT	
10347245	Not Issued	041	01/21/2003	SERIAL LAMP ASSEMBLY FOR EXTENDING ITS LIFE OF USE	CHANG, MEI- FANG
10250199	Not Issued	041	06/12/2003	[ORGANIC LIGHT EMITTING DIODE DISPLAY DEVICE]	CHANG, MEI- YING
10124309 2003 0194493	Not Issued	071 1734	04/16/2002 11/1/2002 L. F. Lin	MULTI-STATION DEPOSITION APPARATUS AND METHOD	CHANG, MEI FFW
09480313	6193836	150	01/10/2000	CENTER GAS FEED APPARATUS FOR A HIGH DENSITY PLASMA REACTOR	CHANG, MEI
09182955	6432479	150	10/29/1998	METHOD FOR IN-SITU, POST DEPOSITION SURFACE PASSIVATION OF A CHEMICAL VAPOR DEPOSITED FILM	CHANG, MEI
09179905	5990565	150	10/28/1998	FLIP CHIP PACKAGE	CHANG MEI LIEN
08982727	6063441	150	12/02/1997	PROCESSING CHAMBER AND METHOD FOR CONFINING PLASMA	CHANG, MEI
08960104	6184150	150	10/27/1997	OXIDE ETCH PROCESS WITH HIGH SELECTIVITY TO NITRIDE SUITABLE FOR USE ON SURFACES OF UNEVEN TOPOGRAPHY	CHANG, MEI
08939962	5882419	150	09/29/1997	IMPROVED CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG, MEI
08939914	5989999	150	09/26/1997	CONSTRUCTION OF A TANTALUM NITRIDE FILM ON A SEMICONDUCTOR WAFER	CHANG, MEI
08682844	5834068	150	07/12/1996	WAFER SURFACE TEMPERATURE CONTROL FOR DEPOSITION OF THIN FILMS	CHANG, MEI
08677185	6155198	150	07/09/1996	APPARATUS FOR CONSTRUCTING AN OXIDIZED FILM ON A SEMICONDUCTOR WAFER	CHANG, MEI
08661807	Not Issued	163	06/11/1996	SHADOW RING FOR SEMICONDUCTOR PROCESSING	CHANG, MEI
08439630	5581238	150	05/12/1995	PACIFIER WITH FEVER HEAT ALARM DEVICE	CHANG, MEI- HUI
08433107	Not Issued	168	05/03/1995	CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM	CHANG, MEI

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				THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS	
<u>08364022</u>	<u>5482749</u>	250	12/23/1994	PRETREATMENT PROCESS FOR TREATING ALUMINUM- BEARING SURFACES OF DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON SUBSTRATE THEREIN	CHANG , MEI
<u>08138179</u>	Not Issued	166 <i>WJ</i>	10/14/1993	PRETREATMENT PROCESS FOR TREATING ALUMINUM- BEARING SURFACES OF DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON SUBSTRATE THEREIN	CHANG , MEI
<u>08135202</u>	<u>5565382</u>	150	10/12/1993 <i>WJ</i>	PROCESS AND APPARATUS FOR FORMING TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFER USING DICHLOROSILANE GAS	CHANG , MEI
<u>08113149</u>	Not Issued	169 <i>WJ</i>	08/26/1993	PROCESS FOR SELECTIVE DEPOSITION OF TUNGSTEN ON SEMICONDUCTOR WAFER	CHANG , MEI
<u>08098538</u>	<u>5449410</u>	250	07/28/1993	PLASMA PROCESSING APPARATUS	CHANG , MEI
<u>07899217</u>	<u>5712327</u>	150	06/16/1992	SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED CLINICAL PERFORMANCE	CHANG , MEI <i>ZYH</i>
<u>07855124</u>	Not Issued	166 <i>WJ</i>	03/18/1992	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI
<u>07823942</u>	<u>5304248</u>	150	01/22/1992	PASSIVE SHIELD FOR CVD WAFER PROCESSING WHICH PROVIDES FRONTSIDE EDGE EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS	CHANG , MEI
<u>07587523</u>	Not Issued	168 <i>WJ</i>	09/21/1990	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI
<u>07551156</u>	Not Issued	166 <i>WJ</i>	07/11/1990	SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED CLINICAL PERFORMANCE	CHANG , MEI- ZYH

<u>07544934</u>	Not Issued	161 <i>OK</i>	06/28/1990	SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED CLINICAL PERFORMANCE	CHANG , MEI ZYH
<u>07407261</u>	Not Issued	161	09/14/1989	SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED SURFACE WETTABILITY	CHANG , MEI Z.
<u>07398689</u>	Not Issued	166 <i>OK</i>	08/25/1989	CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS	CHANG , MEI
<u>07398239</u>	5075256	250	08/25/1989	PROCESS FOR REMOVING DEPOSITS FROM BACKSIDE AND END EDGE OF SEMICONDUCTOR WAFER WHILE PREVENTING REMOVAL OF MATERIALS FROM FRONT SURFACE OF WAFER	CHANG , MEI
<u>07381587</u>	Not Issued	161 <i>OK</i>	07/18/1989	SOFT GAS PERMEABLE CONTACT LENS HAVING IMPROVED SURFACE WETTABILITY	CHANG , MEI Z.
<u>07343035</u>	Not Issued	166	04/25/1989	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR AND METHOD	CHANG , MEI
<u>07251928</u>	Not Issued	166	09/29/1988	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI
<u>07227302</u>	Not Issued	161	08/02/1988	DUAL LAYERED CONTACT LENSES	CHANG , MEI
<u>07147594</u>	Not Issued	164	01/22/1988	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR	CHANG , MEI
<u>07132174</u>	Not Issued	161 <i>OK</i>	12/14/1987	WETTABLE, HYDROPHILIC, SOFT AND OXYGEN PERMEABLE COPOLYMER COMPOSITIONS	CHANG , MEI ZYH
<u>07085424</u>	4854263	150	08/14/1987	INLET MANIFOLD AND METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG , MEI
<u>07067210</u>	Not Issued	166 <i>OK</i>	06/26/1987	REACTOR CHAMBER SELF-CLEANING PROCESS	CHANG , MEI
<u>07001149</u>	Not	169 <i>OK</i>	01/07/1987	WETTABLE, SOFT AND	CHANG , MEI Z.

	Issued	<i>aka</i>		OXYGEN PERMEABLE COPOLYMER COMPOSITIONS	
<u>06944843</u>	Not Issued	166	12/19/1986	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR	CHANG , MEI
<u>06944491</u>	Not Issued	166 <i>aka</i>	12/19/1986	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI

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09311449	6179925	150	05/14/1999	METHOD AND APPARATUS FOR IMPROVED CONTROL OF PROCESS AND PURGE MATERIAL IN SUBSTRATE PROCESSING SYSTEM	CHANG , MEI
09030555	6171661	150	02/25/1998	DEPOSITION OF COPPER WITH INCREASED ADHESION	CHANG , MEI
09023866	6079356	150	02/13/1998	REACTOR OPTIMIZED FOR CHEMICAL VAPOR DEPOSITION OF TITANIUM	CHANG , MEI
09023852	6106625	150	02/13/1998	REACTOR USEFUL FOR CHEMICAL VAPOR DEPOSITION OF TITANIUM NITRIDE	CHANG , MEI
09008796	6291343	150	01/20/1998	PLASMA ANNEALING OF SUBSTRATES TO IMPROVE ADHESION	CHANG , MEI
09001627	Not Issued	161	12/31/1997	ELECTRIC CONNECTOR STRUCTURE	CHANG , MEI LAN
08996735	6099649	150	12/23/1997	CHEMICAL VAPOR DEPOSITION HOT-TRAP FOR UNREACTED PRECURSOR CONVERSION AND EFFLUENT REMOVAL	CHANG , MEI
08884811	6309713	150	06/30/1997	DEPOSITION OF TUNGSTEN NITRIDE BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG , MEI
08857847	5964947	150	05/16/1997	REMOVABLE PUMPING CHANNEL LINERS WITHIN A CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG , MEI

08764471	6297152	150	12/12/1996	CVD PROCESS FOR DCS-BASED TUNGSTEN SILICIDE	CHANG, MEI
08755219	Not Issued	168	11/22/1996	HIGH TEMPERATURE RESISTIVE HEATER	CHANG, MEI
08746178	5773100	150	11/06/1996	PECVD OF SILICON NITRIDE FILMS	CHANG, MEI
08743929	5817576	150	11/05/1996	UTILIZATION OF SIH ₄ SOAK AND PURGE IN DEPOSITION PROCESSES	CHANG, MEI
08734978	6663713	150	10/22/1996	METHOD AND APPARATUS FOR FORMING A THIN POLYMER LAYER ON AN INTEGRATED CIRCUIT STRUCTURE	CHANG, MEI
08717780	6066836	150	09/23/1996	HIGH TEMPERATURE RESISTIVE HEATER FOR A PROCESS CHAMBER	CHANG, MEI
08680724	5846332	150	07/12/1996	THERMALLY FLOATING PEDESTAL COLLAR IN A CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG, MEI
08678490	Not Issued	163	07/09/1996	METHOD FOR CLEANING TUNGSTEN CVD CHAMBERS USING MOLECULAR FLUORINE WITHOUT PLASMA EXCITATION	CHANG, MEI
08666976	5780360	150	06/20/1996	DICHLOROSILANE PURGE IN SILICIDE DEPOSITION PROCESSES	CHANG, MEI
08639411	5874362	150	04/29/1996	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG, MEI
08605809	6103014	150	02/23/1996	CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG, MEI
08570764	Not Issued	161	12/12/1995	CENTER GAS FEED APPARATUS FOR A HIGH DENSITY PLASMA REACTOR	CHANG, MEI
08565184	Not Issued	166	11/28/1995	OXIDE ETCH PROCESS WITH HIGH SELECTIVITY TO NITRIDE SUITABLE FOR USE ON SURFACES OF UNEVEN TOPOGRAPHY	CHANG, MEI
08551397	Not Issued	161	11/01/1995	LOW TEMPERATURE PROCESS FOR CVD FORMATION OF LOW RESISTIVITY TITANIUM	CHANG, MEI

		<i>all</i>		NITRIDE ON A SEMICONDUCTOR WAFER	
<u>08453135</u>	Not Issued	166 <i>all</i>	05/24/1995	INLET MANIFOLD AND METHOD FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG , MEI
<u>08450604</u>	Not Issued	166 <i>all</i>	05/25/1995	SHADOW RING FOR SEMICONDUCTOR PROCESSING	CHANG , MEI
<u>08438820</u>	Not Issued	161 <i>all</i>	05/11/1995	APPARATUS FOR FORMING TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFER USING DICHLOROSILANE GAS	CHANG , MEI
<u>08342522</u>	<u>5856240</u>	150	11/21/1994 ?	CHEMICAL VAPOR DEPOSITION OF A THIN FILM ONTO A SUBSTRATE	CHANG , MEI
<u>08327126</u>	6123864	150	10/21/1994	ETCH CHAMBER	CHANG , MEI
<u>08229863</u>	Not Issued	166 <i>all</i>	04/19/1994	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI
<u>08218209</u>	5851299	150	03/25/1994	PASSIVE SHIELD FOR CVD WAFER PROCESSING WHICH PROVIDES FRONTSIDE EDGE EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS	CHANG , MEI
<u>08200862</u>	5695568	150	02/23/1994	CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG , MEI
<u>08187231</u>	5421401	150	01/25/1994	COMPOUND CLAMP RING FOR SEMICONDUCTOR WAFERS	CHANG , MEI
<u>08145432</u>	Not Issued	163 <i>all</i>	10/29/1993	SHADOW RING FOR SEMICONDUCTOR PROCESSING	CHANG , MEI
<u>08136529</u>	Not Issued	166 <i>all</i>	10/14/1993	DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE	CHANG , MEI
<u>08113025</u>	Not Issued	161 <i>all</i>	08/27/1993	PROCESS FOR SELECTIVE DEPOSITION OF TUNGSTEN ON SEMICONDUCTOR WAFER	CHANG , MEI
<u>08091698</u>	Not	166 <i>all</i>	07/14/1993	LOW TEMPERATURE	CHANG , MEI

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	Issued	<i>del</i>		PROCESS FOR CVD FORMATION OF LOW RESISTIVITY TITANIUM NITRIDE ON A SEMICONDUCTOR WAFER	
<u>08083420</u>	Not Issued	166 <i>del</i>	06/28/1993	PROCESS FOR UNIFORM DEPOSITION OF TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFERS BY TREATMENT OF SUSCEPTOR HAVING ALUMINUM NITRIDE SURFACE THEREON WITH TUNGSTEN SILICIDE AFTER CLEANING OF SUSCEPTOR	CHANG, MEI
<u>08042961</u>	Not Issued	166 <i>del</i>	04/05/1993	CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG, MEI
<u>07947212</u>	5316278	150	09/18/1992	CLAMPING RING APPARATUS FOR PROCESSING SEMICONDUCTOR WAFERS	CHANG, MEI
<u>07894180</u>	5207836	150	06/03/1992	CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS	CHANG, MEI
<u>07809050</u>	Not Issued	166 <i>del</i>	12/17/1991	INLET MANIFOLD AND METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG, MEI
<u>07760848</u>	5215619	150	09/17/1991	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR	CHANG, MEI
<u>07759319</u>	5213650	150	09/13/1991	APPARATUS FOR REMOVING DEPOSITS FROM BACKSIDE AND END EDGE OF SEMICONDUCTOR WAFER WHILE PREVENTING REMOVAL OF MATERIALS FROM FRONT SURFACE OF WAFER	CHANG, MEI
<u>07709809</u>	Not Issued	166 <i>del</i>	05/31/1991	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG, MEI
<u>07622664</u>	Not Issued	161 <i>del</i>	12/05/1990	PASSIVE SHIELD FOR CVD WAFER PROCESSING WHICH PROVIDES FRONTSIDE EDGE	CHANG, MEI

		<i>abd</i>		EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS	
<u>07595793</u>	Not Issued	166 <i>abd</i>	10/09/1990	MAGNETIC FIELD- ENHANCED PLASMA ETCH REACTOR	CHANG , MEI
<u>07587523</u>	Not Issued	168	09/21/1990	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG , MEI
<u>07345977</u>	Not Issued	166 <i>abd</i>	04/28/1989	METHODS FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG , MEI
<u>07338215</u>	4943997	150	04/14/1989	DEVICE FOR COMMUNICATING A DOORSIDE INTERCOM SET WITH A REMOTE TELEPHONE	CHANG , MEI-YIN
<u>07337607</u>	4962049	150	04/13/1989	PROCESS FOR THE PLASMA TREATMENT OF THE BACKSIDE OF A SEMICONDUCTOR WAFER	CHANG , MEI
<u>07026836</u>	Not Issued	161	03/17/1987	WETTABLE HYDROPHILIC, SOFT AND OXYGEN PERMEABLE COPOLYMER COMPOSITIONS	CHANG , MEI Z.

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Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>60067130</u>	Not Issued	159	12/02/1997	CHEMICAL VAPOR DEPOSITION <u>HARDWARE</u>	CHANG , MEI
<u>09409477</u>	6129044	150	10/06/1999	APPARATUS FOR SUBSTRATE PROCESSING WITH IMPROVED THROUGHPUT AND YIELD	CHANG , MEI
<u>09379734</u>	Not Issued	161 <i>also</i>	08/24/1999	GOLF BALL HAVING A IDENTIFICATION LAYER INTER DISPOSED BETWEEN THE CORE AND THE OUTER LAYER	CHANG , MEI-TZU
<u>09378132</u>	<u>6159867</u>	150	08/19/1999 ?	RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG , MEI
<u>09344825</u>	<u>6214714</u>	150	06/25/1999	METHOD OF TITANIUM/TITANIUM NITRIDE INTEGRATION	CHANG , MEI
<u>09322921</u>	6131992	150	06/01/1999	FOLDABLE CHAIR SUPPORTED BY REAR SUPPORTING LEGS	CHANG , MEI-FANG
<u>09314999</u>	Not Issued	163 <i>also</i>	05/19/1999	UTILIZATION OF <u>SiH4</u> SOAK AND PURGE IN DEPOSITION PROCESSES	CHANG , MEI
<u>09248183</u>	<u>6365495</u>	150	02/09/1999	METHOD FOR PERFORMING METALLO-ORGANIC CHEMICAL VAPOR DEPOSITION OF TITANIUM NITRIDE AT REDUCED TEMPERATURE	CHANG , MEI
<u>09200104</u>	Not Issued	164 <i>also</i>	11/25/1998	METHOD FOR CVD WAFER PROCESSING WHICH	CHANG , MEI

no

		<i>del</i>		PROVIDES FRONTSIDE EDGE EXCLUSION AND PREVENTS BACKSIDE DEPOSITIONS	
<u>09179904</u>	Not Issued	161 <i>del</i>	10/28/1998	IC PACKAGE CAPABLE OF CONDUCTING HEAT/ELECTRICITY AND REDUCING INDUCTANCE	CHANG, MEI-LIEN
<u>09134290</u>	<u>6020270</u>	150	08/14/1998	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG, MEI
<u>09108950</u>	<u>6027606</u>	150	06/30/1998	CENTER GAS FEED APPARATUS FOR A HIGH DENSITY PLASMA REACTOR	CHANG, MEI
<u>09096996</u>	Not Issued	164 <i>del</i>	06/13/1998	CONTROLLED ADDITION OF WATER DURING CHEMICAL VAPOR DEPOSITION OF COPPER TO IMPROVE ADHESION	CHANG, MEI
<u>09092477</u>	<u>6319728</u>	150	06/05/1998	METHOD FOR TREATING A DEPOSITED FILM FOR RESISTIVITY REDUCTION	CHANG, MEI
<u>09087083</u>	<u>5957061</u>	150	05/29/1998	BANQUET TABLE	CHANG, MEI-FANG
<u>09071514</u>	<u>6294466</u>	150	05/01/1998	HDP-CVD APPARATUS AND PROCESS FOR DEPOSITING TITANIUM FILMS FOR SEMICONDUCTOR DEVICES	CHANG, MEI
<u>09059734</u>	<u>6040022</u>	150	04/14/1998	PECVD OF COMPOUNDS OF SILICON FROM SILANE AND NITROGEN	CHANG, MEI
<u>09055689</u>	<u>6296712</u>	150	04/06/1998	CHEMICAL VAPOR DEPOSITION HARDWARE AND PROCESS	CHANG, MEI
<u>09049856</u>	<u>6270859</u>	150	03/27/1998 <i>TiN</i>	PLASMA TREATMENT OF TITANIUM NITRIDE FORMED BY CHEMICAL VAPOR DEPOSITION	CHANG, MEI
<u>09026042</u>	<u>6395128</u>	150	02/19/1998 <i>?</i>	RF POWERED PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION REACTOR AND METHODS OF EFFECTING PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG, MEI
<u>08982872</u>	Not Issued	161 <i>del</i>	12/02/1997	IN-SITU, PRECLEAN OF WAFERS PRIOR TO A	CHANG, MEI

		<i>abst</i>		CHEMICAL VAPOR DEPOSITION TITANIUM DEPOSITION STEP	
<u>08918665</u>	<u>5983906</u>	150	08/22/1997	METHODS AND APPARATUS FOR A <u>CLEANING PROCESS</u> IN A HIGH TEMPERATURE, CORROSIVE, PLASMA ENVIRONMENT	CHANG , MEI
<u>08884811</u>	<u>6309713</u>	150	06/30/1997 <i>WN</i>	DEPOSITION OF <u>TUNGSTEN</u> <u>NITRIDE</u> BY PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION	CHANG , MEI
<u>08808246</u>	<u>6699530</u>	150	02/28/1997 <i>?</i>	METHOD FOR <u>CONSTRUCTING</u> A <u>FILM</u> ON A — SEMICONDUCTOR WAFER	CHANG , MEI
<u>08604351</u>	Not Issued	161 <i>abst</i>	02/21/1996	DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE	CHANG , MEI
<u>08574739</u>	Not Issued	161 <i>abst</i>	12/19/1995	PRECONDITIONING PROCESS FOR TREATING DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON ACTIVE SUBSTRATES THEREIN	CHANG , MEI
<u>08504294</u>	<u>5510297</u>	150	08/10/1995	PROCESS FOR UNIFORM DEPOSITION OF <u>TUNGSTEN</u> <u>SILICIDE</u> ON SEMICONDUCTOR WAFERS BY TREATMENT OF SUSCEPTOR HAVING ALUMINUM NITRIDE SURFACE THEREON WITH TUNGSTEN SILICIDE AFTER CLEANING OF SUSCEPTOR	CHANG , MEI
<u>08352265</u>	Not Issued	166 <i>abst</i>	12/07/1994	PROCESS FOR UNIFORM DEPOSITION OF TUNGSTEN SILICIDE ON SEMICONDUCTOR WAFERS BY TREATMENT OF SUSCEPTOR HAVING ALUMINUM NITRIDE SURFACE THEREON WITH TUNGSTEN SILICIDE AFTER CLEANING OF SUSCEPTOR	CHANG , MEI
<u>08342670</u>	<u>5516367</u>	150	11/21/1994	CHEMICAL VAPOR	CHANG , MEI

				DEPOSITION CHAMBER WITH A PURGE GUIDE.	
08326506	5855687	150	10/20/1994	SUBSTRATE SUPPORT SHIELD IN WAFER PROCESSING REACTORS	CHANG, MEI
08314161	Not Issued	166	09/27/1994	UTILIZATION OF SIH ₄ SOAK AND PURGE IN DEPOSITION PROCESSES	CHANG, MEI
08296042	Not Issued	161	08/23/1994	METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER	CHANG, MEI
08272959	Not Issued	166	07/11/1994	INLET MANIFOLD AND METHOD FOR INCREASING GAS DISSOCIATION AND FOR PECVD OF DIELECTRIC FILMS	CHANG, MEI
08085064	Not Issued	169	06/29/1993	PLASMA PROCESSING APPARATUS	CHANG, MEI
08084333	Not Issued	166	06/28/1993	BROMINE AND IODINE ETCH PROCESS FOR SILICON AND SILICIDES	CHANG, MEI
08078364	5356835	150	06/16/1993	METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER	CHANG, MEI
08071462	Not Issued	166	06/02/1993	ETCH CHAMBER	CHANG, MEI
08032909	Not Issued	161	03/18/1993	CLEANING PROCESS FOR REMOVAL OF DEPOSITS FROM THE SUSCEPTOR OF A CHEMICAL VAPOR DEPOSITION APPARATUS	CHANG, MEI
08031259	5326725	150	03/11/1993	CLAMPING RING AND SUSCEPTOR THEREFOR	CHANG, MEI
07968710	Not Issued	161	10/30/1992	METHOD FOR PROCESSING SEMICONDUCTOR WAFERS AT TEMPERATURES EXCEEDING 400 C	CHANG, MEI
07778326	5219485	150	10/17/1991	MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON AND POLYCIDES	CHANG, MEI
07707214	Not	166	05/23/1991	CLEANING PROCESS FOR	CHANG, MEI

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07704523	5201990	150	05/23/1991	PROCESS FOR TREATING ALUMINUM SURFACES IN A VACUUM APPARATUS	CHANG , MEI
07677681	5250467	150	03/29/1991	METHOD FOR FORMING LOW RESISTANCE AND LOW DEFECT DENSITY TUNGSTEN CONTACTS TO SILICON SEMICONDUCTOR WAFER	CHANG , MEI
07455799	4960488	150	12/19/1989	REACTOR CHAMBER SELF-CLEANING PROCESS	CHANG , MEI
07444485	5043299	250	12/01/1989	PROCESS FOR SELECTIVE DEPOSITION OF TUNGSTEN ON SEMICONDUCTOR WAFER	CHANG , MEI
07443811	5112435	150	11/29/1989	MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON AND POLYCIDES	CHANG , MEI
07411189	Not Issued	166 and	09/20/1989	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR	CHANG , MEI
07398653	5028565	250	08/25/1989	PROCESS FOR CVD DEPOSITION OF TUNGSTEN LAYER ON SEMICONDUCTOR WAFER	CHANG , MEI
07185256	Not Issued	166 and	04/19/1988	MATERIALS AND METHODS FOR ETCHING SILICIDES, POLYCRYSTALLINE SILICON & POLYCIDES	CHANG , MEI
07185215	4842683	150	04/25/1988	MAGNETIC FIELD-ENHANCED PLASMA ETCH REACTOR	CHANG , MEI

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09163711	6242347	150	09/30/1998	METHOD FOR CLEANING A PROCESS CHAMBER	CHANG , MEI
09140818	6090706	150	08/26/1998	PRECONDITIONING PROCESS FOR TREATING DEPOSITION CHAMBER PRIOR TO DEPOSITION OF TUNGSTEN SILICIDE COATING ON ACTIVE SUBSTRATES THEREIN	CHANG , MEI
08606267	5935338	150	02/23/1996	CHEMICAL VAPOR DEPOSITION CHAMBER	CHANG , MEI
08604351	Not Issued	161	02/21/1996	DEPOSITION OF ADHERENT TUNGSTEN SILICIDE FILMS FROM DICHLOROSILANE AND TUNGSTEN HEXAFLUORIDE	CHANG , MEI

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3	L4	1967	3 and (TiN.m/c. TiNSi "Ti-N-Si" TiSiN "Ti-Si-N" titanium nitride)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 15:58
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